



NOTES:

1. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE "Z".
2. DATUM "Z" IS DEFINED BY THE SPERICAL CROWNS OF THE SOLDER BALLS.
3. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
4. ALL DIMENSIONS ARE IN MILLIMETERS.
5. DIMENSIONING AND TOLERANCING PER ASME Y14.5M.



TITLE: PACKAGE OUTLINE,  
144 BALL CSBGA, 12x12x1.4mm, 0.8mm PITCH

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